

A WIRE HOLDING APPARATUS FOR WIRE BONDING**ABSTRACT OF THE DISCLOSURE**

- 5 An apparatus for holding a wire during a wire bonding process is provided. The apparatus includes a body having a left body and a right body, a wire guide coupled to the left body for feeding the wire, at least two wire contact surfaces for providing suitable gripping on the wire such that one of the at least two wire contact surfaces is coupled to the left body and the other of the at least two wire contact surfaces is
- 10 coupled to the right body and a force application mechanism coupled to the wire contact surface of the right body, wherein the force application mechanism exerts a holding force on the wire to hold the wire throughout the wire bonding process until a time of wire tail cutting.
- 15 Figure 2 accompanies the abstract.